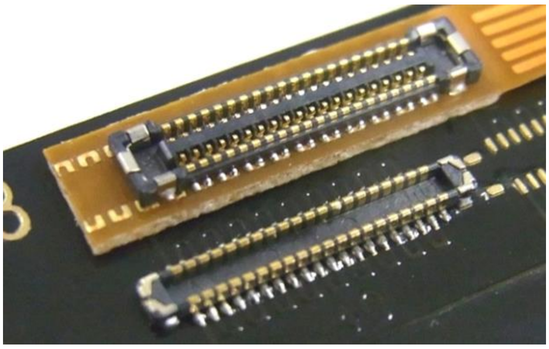
BM23FR Series

0.35mm Pitch, 0.6mm & 0.8mm Stacking Height, Board to FPC Connectors



◆Features

1. Space saving: 0.35mm pitch, 0.6mm & 0.8mm stacking height, 1.98mm depth
2. Robust structure with metal covered guidance ribs
3. Wide vacuum pick & place area configured in space with 1.98mm depth
4. Easy mating operation by clear tactile click and wide self alignment range
5. Highly reliable 2-point contact
6. Supports USB 3.1 gen.2 (10Gbps) transmission
7. Solder wicking prevention
8. Contact protection against dust

◆Specifications

・Material and Finish

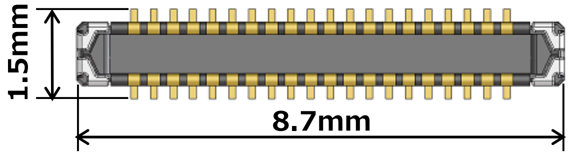
COMPONENT	MATERIAL	FINISH
Housing	LCP	Black, UL94V-0
Contact	Phosphor bronze	Gold plated over Nickel under plating
Metal Fitting	Phosphor bronze	Gold plated over Nickel under plating

・Performance Characteristics

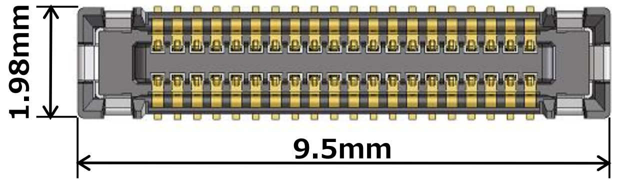
Rated Current	0.3A
Rated Voltage	30V AC/DC
Operating Temperature	-55°C to +85°C (Include the temperature rising by current flow)
Contact Resistance	100mΩ Max. (20mV AC or 1000Hz)
Withstanding Voltage	100V AC for 1 minute
Insulation Resistance	50MΩ or above (100V DC)
Durability	10 cycles

◆Dimensions (40pos.)

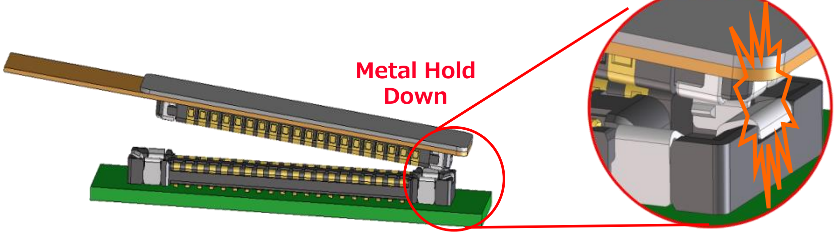
・Header



・Receptacle



◆Robust Structure: Breaking Strength 90N



If the header and the receptacle should be mated offset incorrectly, the metal hold down would ease the impact and prevent the housing from cracking and breaking.

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